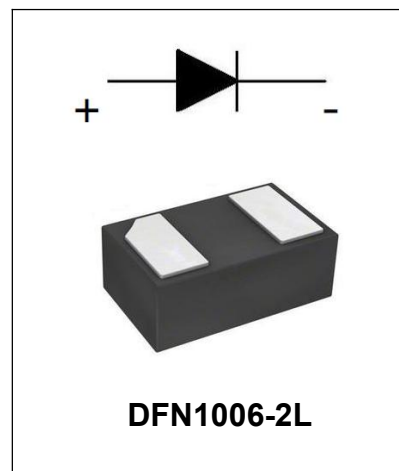


Features

- ◆ Low Forward Voltage Drop
- ◆ Small Surface Mounting Type
- ◆ RoHS Compliant
- ◆ Green EMC
- ◆ Band Indicates Cathode
- ◆ Weight: approx. 0.001g



Maximum Rating @ Ta=25°C unless otherwise specified

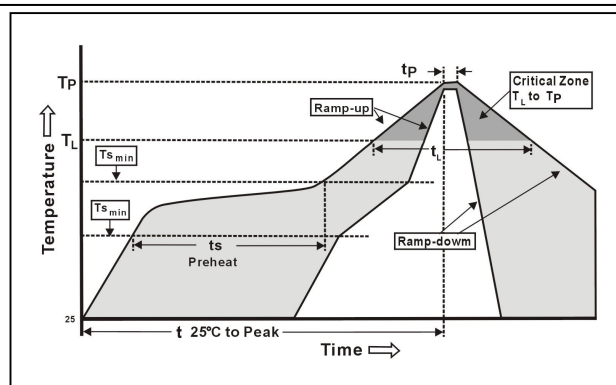
| Symbol | Parameter | Value | Units |
|--------------------|--------------------------------|-------------|-------|
| P _D | Power Dissipation | 150 | mW |
| T _{STG} | Storage Temperature Range | -55 to +125 | °C |
| T _J | Operating Junction Temperature | +125 | °C |
| V _R | DC Reverse Voltage | 30 | V |
| I _{F(AV)} | Average Forward Current | 200 | mA |
| I _{FSM} | Peak Forward Surge Current | 1 | A |

Electrical Characteristics@ Ta=25°C unless otherwise

| Symbol | Parameter | Test Condition | Limits | | Unit |
|--------|-------------------------|----------------|--------|-----|------|
| | | | Min | Max | |
| IR | Reverse Leakage Current | VR=10V | | 30 | μA |
| VF | Forward Voltage | IF=20mA | | 0.4 | V |
| | | IF=200mA | | 0.5 | V |

Soldering Parameters

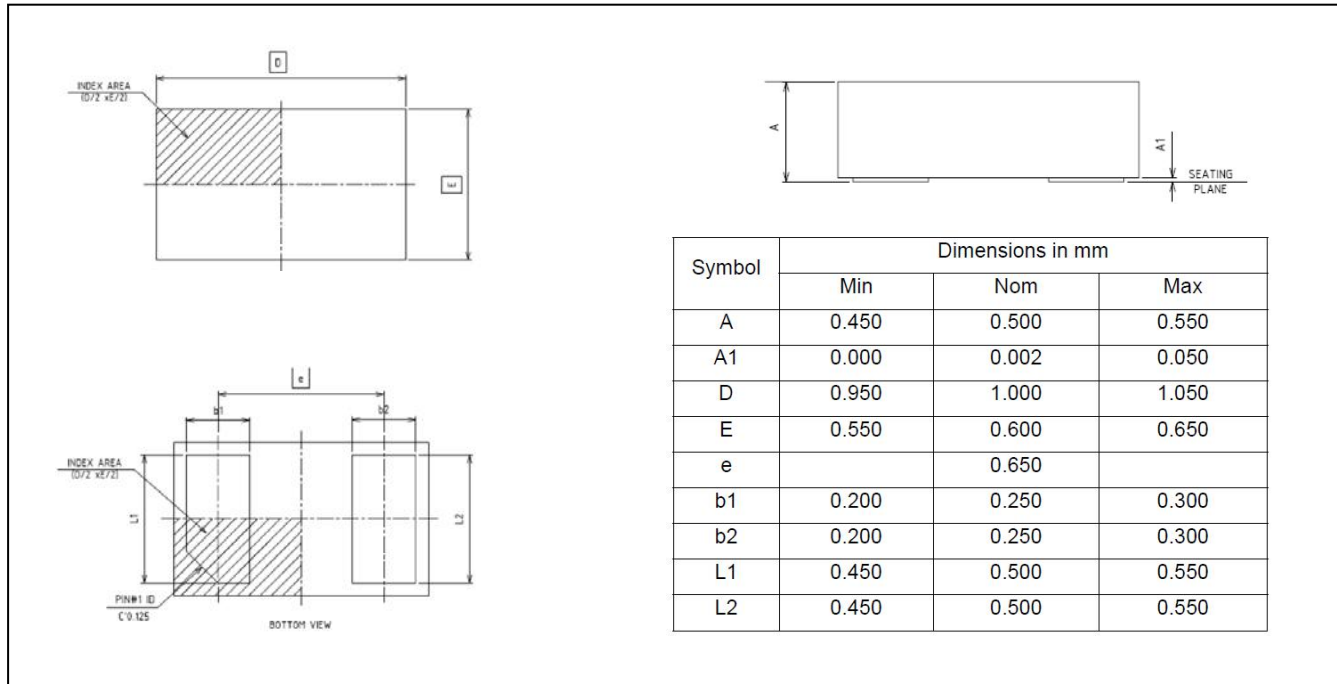
| | | |
|--|------------------------------------|-------------------------|
| Reflow Condition | | Fb – Free assembly |
| Pre Heat | - Temperature Min ($T_{s(Min)}$) | 150°C |
| | - Temperature Max ($T_{s(Max)}$) | 200°C |
| | - Time (Min to max) (t_s) | 60 – 180 secs |
| Average ramp up rate (Liquidus) Temp (T_L) to peak | | 3°C/second Max |
| $T_{s(Max)}$ to T_L - Ramp-up Rate | | 3°C/second Max |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | - Temperature (t_l) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 250 ^{+0/-5} °C |
| Time within 5°C of actual peak Temperature (t_p) | | 20 – 40 seconds |
| Ramp-down Rate | | 6°C/second Max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes Max. |
| Do not exceed | | 260°C |



Package Outline

Plastic surface mounted package

DFN1006-2L



Package Information

| Device | Package | Shipping | Reel Size |
|--------|------------|------------|-----------|
| TAPING | DFN1006-2L | 10000/Reel | 7 inch |

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